



Advanced Packaging Process Chemistry

From deposition to final clean

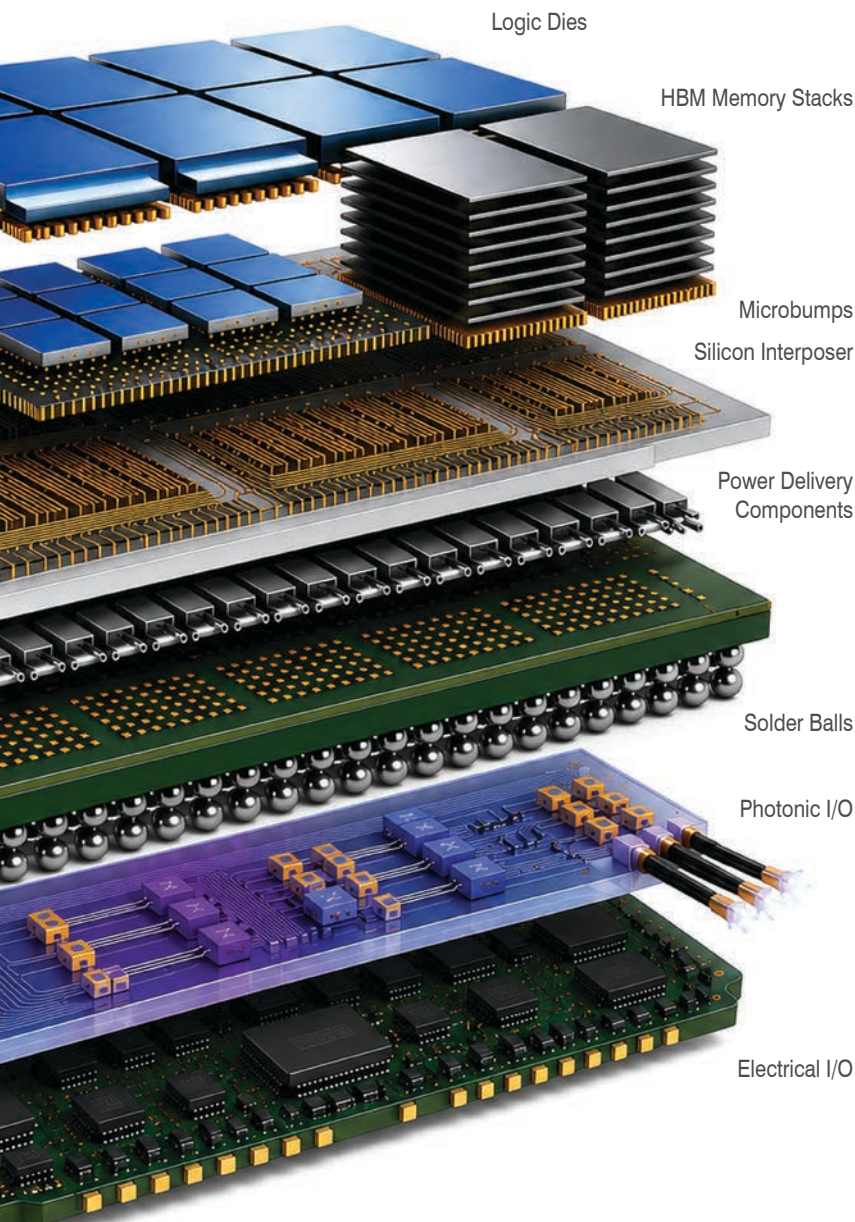


The Technic Advantage

As device geometries become more complex, the need for precise chemical control intensifies. Technic develops and manufactures **Electrodeposition, Strip, Etch, and Clean chemistries** that deliver consistent performance across diverse materials and device structures. From fine-line RDL to TSVs and copper pillars, our portfolio supports critical wafer and full panel-level manufacturing processes.

Technic combines

- Local manufacturing of high-quality chemistry, backed by an established global supply network
- Decades of wet-process expertise in high-volume manufacturing environments
- Continuous product development driven by global R&D teams
- Advanced Engineered Solutions - integrated chemistry, analytics, and global support for rapid implementation and optimization



Core Technology Platforms

Elevate®

Advanced Electrodeposition Chemistries

Electrodeposition technologies that enable advanced interconnect structures throughout today's heterogeneous semiconductor packages.

- Redistribution layers (RDL)
- Through-silicon vias (TSVs)
- Copper pillars and microbumps
- Precious, specialty and alloy metal deposition
- Advanced semiconductor packaging

TechniStrip®

Advanced Strip Chemistries

Advanced stripping chemistries designed for critical wafer fabrication and advanced packaging.

- Photoresist removal
- Polymer and residue removal
- Temporary bonding material removal
- Post-etch cleaning
- Advanced wafer and package processing

TechniEtch

Precision Etch Chemistries

Precision wet etch chemistries for advanced semiconductor fabrication and packaging.

- Metal and barrier layer etching
- Seed layer removal
- Dielectric and specialty material etching
- Surface preparation for subsequent processes
- Advanced device fabrication

TechniClean

Surface Preparation & Cleaning

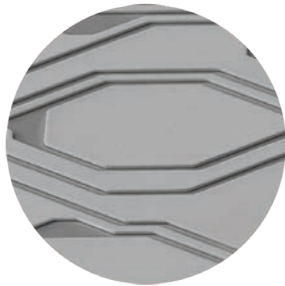
Surface preparation and cleaning chemistries that help maximize process yield, device performance, and long-term reliability.

- Surface preparation
- Particle, residue & metal contamination removal
- Post-process cleaning
- Surface conditioning
- Device reliability

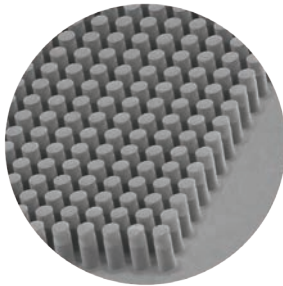
Industry-Leading Product Portfolio



Elevate® Cu 3000



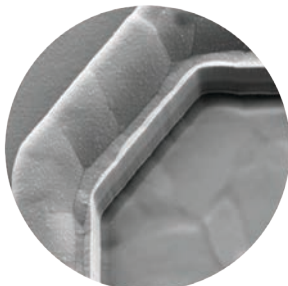
Elevate® Gold 7990 NBV HT



TechniStrip® NF52/NF90



TechniEtch TBR19



TechniClean CA 25

Elevate®

Elevate® Cu 3000

Copper electrodeposition for RDL, copper pillars, and advanced interconnects.

Elevate® Cu 1500

MSA copper process for high-performance TSV via filling.

Elevate® Ni 5950

Boric acid-free nickel process for UBM, metal stacks, and via fill.

Elevate® Tin 5011

Pure tin chemistry delivering uniform, fine-grained deposits.

Elevate® Gold 7990 NBV HT

Thallium-, arsenic-, and cyanide-free sulfite gold with long bath life and excellent resist compatibility.

Elevate® AuSn 8020

Single-step gold-tin alloy for high-reliability photonic and semiconductor packaging.



TechniStrip®

TechniStrip® NF Series

Powerful DMSO-based strippers for complete dissolution of P- and N- tone and laminated photoresists, with excellent metal compatibility. TMAH and TMAH-free versions available.

TechniStrip® MLO Series

High-performance DMSO-based formulated strippers for P-tone photoresist, BARC dissolution, and metal lift-off.

TechniStrip® Solvent Blends

NMP-free solvent blends for efficient positive-tone photoresist stripping and lift-off.

TechniStrip® Micro NGA Series

Organic solutions for removing polyimide, BCB and bonding adhesives.

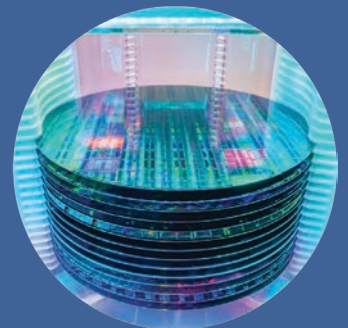
TechniEtch

TechniEtch TBR Series

Fluoride-free titanium/barrier etchant.

TechniEtch Cu Select

Tunable, selective etchant compatible with Ni, Ti, TiW.



TechniClean

TechniClean BOS 390

Single integrated process for fluoropolymer residue cleaning after TSV/Bosch etching with photoresist (P- and N-Tone) removal.

TechniClean CA Series

Post-etch residue removal.



Safer, Cleaner & More Sustainable



Large-Scale Global Manufacturing



Regional Manufacturing & Distribution



Industry-Recognized R&D Leadership



Reliable Global Supply Chain



Quality Manufacturing & Process Control

Sustainable Process Innovation

Technic's R&D teams work with industry and research partners to develop safer alternatives to hazardous chemicals, engineered specifically for the demands of semiconductor manufacturing. NMP and TMAH alternatives, boric acid-free nickel, fluoride-free etchants, and non-cyanide gold all meet fab-grade performance, while reducing reliance on hazardous materials.

Close collaboration between R&D and field engineers accelerates the transition from laboratory development to high-volume production.



Global Reach

Technic operates manufacturing, technical service, and R&D facilities spanning **24 locations** in **14 countries**, providing global support with local expertise for semiconductor manufacturers.

Regional technical centers, aligned with customer fabrication facilities, enable rapid implementation, optimization, and scale-up from development through high-volume production.

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